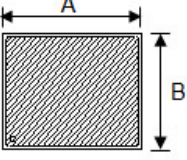
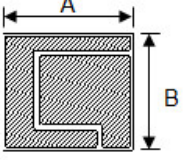
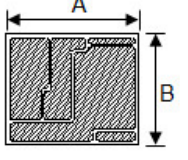
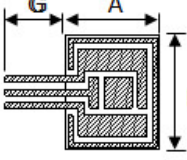
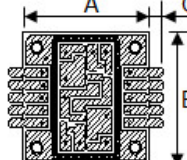
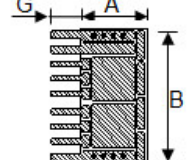



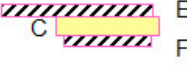




Copper-bonded silicon nitride substrates / packages (for engineering evaluation)

No.	1	2	3	4	5	6
TOP VIEW						
CROSS SECTION						
OVERALL A x B	43.0 x 32.0	25.0 x 20.5	50.8 x 38.1	20.0 x 22.0	44.0 x 41.4	28.0 x 54.8
CERAMIC THICKNESS C / D	0,32	0,32	0,32	0,32	0.32 / 0.635	0.32 / 0.32
Cu THICKNESS E / F	0.2 / 0.2	0.3 / 0.2	0.3 / 0.2	0.5 / 0.5	0.3 / 0.3	0.3 / 0.3
Cu LEAD LENGTH G	–	–	–	13,0	4,5	12,0
Fe-Ni-Co SEAL RING HEIGHT H	–	–	–	–	2,0	–
PACKAGE DRAWING NUMBER	KO-PWR110507 (PLATING: Ni-P) KO-PWR110508 (PLATING: Ni-P / Au) KO-PWR110509 (PLATING: Ni-P / Pd / Ag)	KO-PWR110681	KO-PWR110682	KO-PWR110683	KO-PWR110684	KO-PWR140627 (PLATING: Ni-P) KO-PWR140628 (PLATING: Ni-P / Au) KO-PWR140629 (PLATING: Ni-P / Pd / Au)

Unit: mm

Kyocera reserves the right to modify these specifications without notice. Kyocera Fineceramics GmbH, July 2017